

# NLU1G07

## Single Non-Inverting Buffer with Open Drain Output

The NLU1G07 MiniGate™ is an advanced high-speed CMOS non-inverting buffer with open drain output in ultra-small footprint.

The NLU1G07 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

### Features

- High Speed:  $t_{PD} = 3.8 \text{ ns (Typ) @ } V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu\text{A (Max) at } T_A = 25^\circ\text{C}$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

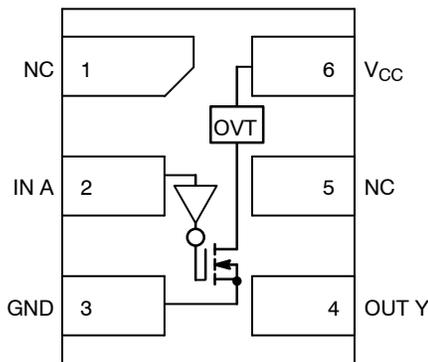


Figure 1. Pinout (Top View)

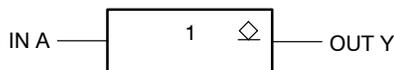


Figure 2. Logic Symbol

### PIN ASSIGNMENT

1	NC
2	IN A
3	GND
4	OUT Y
5	NC
6	V <sub>CC</sub>

### FUNCTION TABLE

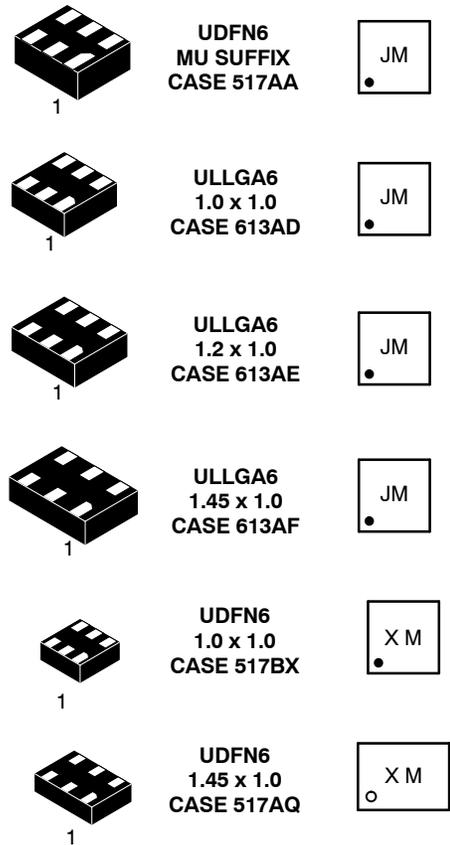
A	Y
L	L
H	Z



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### MARKING DIAGRAMS



J = Device Marking  
M = Date Code

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# NLU1G07

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage	-0.5 to +7.0	V
I <sub>IK</sub>	DC Input Diode Current V <sub>IN</sub> < GND	-20	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>OUT</sub> < GND	±20	mA
I <sub>O</sub>	DC Output Source/Sink Current	±12.5	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±25	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±25	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T <sub>J</sub>	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA / JESD22-A114-A.
3. Tested to EIA / JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA / JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	1.65	5.5	V
V <sub>IN</sub>	Digital Input Voltage	0	5.5	V
V <sub>OUT</sub>	Output Voltage	0	5.5	V
T <sub>A</sub>	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate V <sub>CC</sub> = 3.3 V ± 0.3 V V <sub>CC</sub> = 5.0 V ± 0.5 V	0 0	100 20	ns/V

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## DC ELECTRICAL CHARACTERISTICS

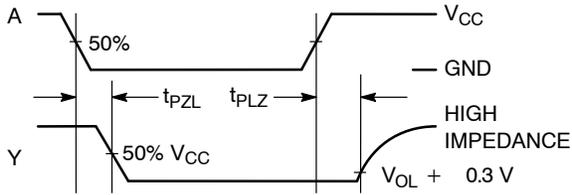
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25 °C			T <sub>A</sub> = +85°C		T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	Low-Level Input Voltage		1.65	0.75 x V <sub>CC</sub>			0.75 x V <sub>CC</sub>				V
			2.3 to 5.5	0.70 x V <sub>CC</sub>			0.70 x V <sub>CC</sub>				
V <sub>IL</sub>	Low-Level Input Voltage		1.65			0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	V
			2.3 to 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>	
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 50 μA	2.0		0	0.1		0.1		0.1	V
			3.0		0	0.1		0.1		0.1	
			4.5		0	0.1		0.1		0.1	
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 4 mA	3.0			0.36		0.44		0.52	V
		I <sub>OL</sub> = 8 mA	4.5			0.36		0.44		0.52	
I <sub>LKG</sub>	Z-State Output Leakage Current	V <sub>IN</sub> = V <sub>IH</sub> , V <sub>OUT</sub> = V <sub>CC</sub> or GND	5.5			±0.25		±2.5		±5.0	μA
I <sub>IN</sub>	Input Leakage Current	0 = V <sub>IN</sub> = 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	μA
I <sub>OFF</sub>	Power off Input Leakage Current	0 ≤ V <sub>IN</sub> , V <sub>OUT</sub> = 5.5 V	0.0			0.25		2.5		5	μA
I <sub>CC</sub>	Quiescent Supply Current	0 ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	5.5			1.0		20		40	μA

## AC ELECTRICAL CHARACTERISTICS (Input t<sub>r</sub> = t<sub>f</sub> = 3.0 ns)

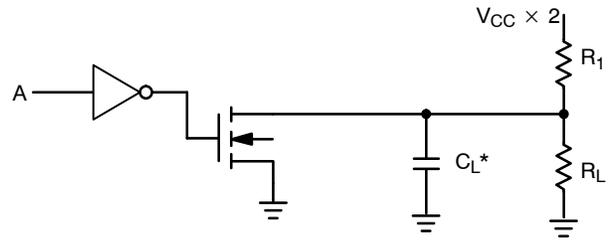
Symbol	Parameter	V <sub>CC</sub> (V)	Test Condition	T <sub>A</sub> = 25 °C			T <sub>A</sub> = +85°C		T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>pZL</sub>	Output Enable Time, Input A to Output Y	3.0 to 3.6	R <sub>L</sub> = R <sub>1</sub> = 50 Ω, C <sub>L</sub> = 15 pF		5.0	7.1		8.5		10.0	ns
			R <sub>L</sub> = R <sub>1</sub> = 50 Ω, C <sub>L</sub> = 50 pF		7.5	10.6		12.0		14.5	
		4.5 to 5.5	R <sub>L</sub> = R <sub>1</sub> = 50 Ω, C <sub>L</sub> = 15 pF		3.8	5.5		6.5		8.0	
			R <sub>L</sub> = R <sub>1</sub> = 50 Ω, C <sub>L</sub> = 50 pF		5.3	7.5		8.5		10.0	
t <sub>PLZ</sub>	Output Disable Time	3.0 to 3.6	R <sub>L</sub> = R <sub>1</sub> = 50 Ω, C <sub>L</sub> = 50 pF		7.5	10.6		12.0		14.5	ns
		4.5 to 5.5	R <sub>L</sub> = R <sub>1</sub> = 50 Ω, C <sub>L</sub> = 50 pF		5.3	7.5		8.5		10.0	
C <sub>IN</sub>	Input Capacitance				4	10		10		10.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	5.0			18						pF

6. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

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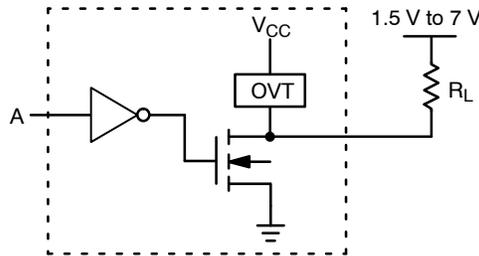


**Figure 3. Switching Waveforms**



\*Includes jig and probe capacitance.  
 $R_L = R_1 = 500 \Omega$

**Figure 4. Test Circuit**



**Figure 5. Output Voltage Mismatch Application**

## ORDERING INFORMATION

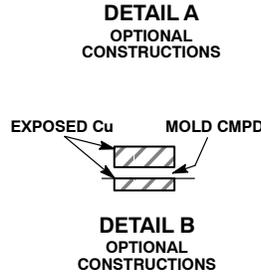
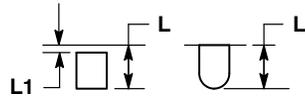
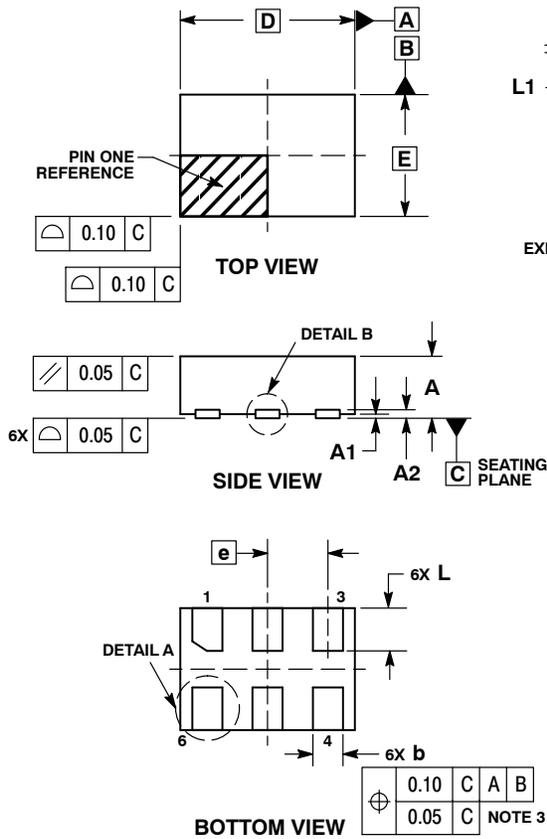
Device	Package	Shipping <sup>†</sup>
NLU1G07MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU1G07AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU1G07BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU1G07CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel
NLU1G07AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU1G07CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P  
CASE 517AQ  
ISSUE O

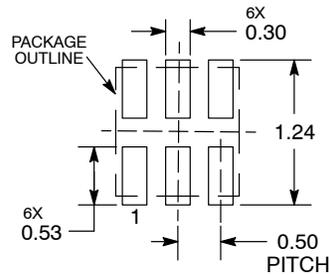


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07	REF
b	0.20	0.30
D	1.45	BSC
E	1.00	BSC
e	0.50	BSC
L	0.30	0.40
L1	---	0.15

### MOUNTING FOOTPRINT



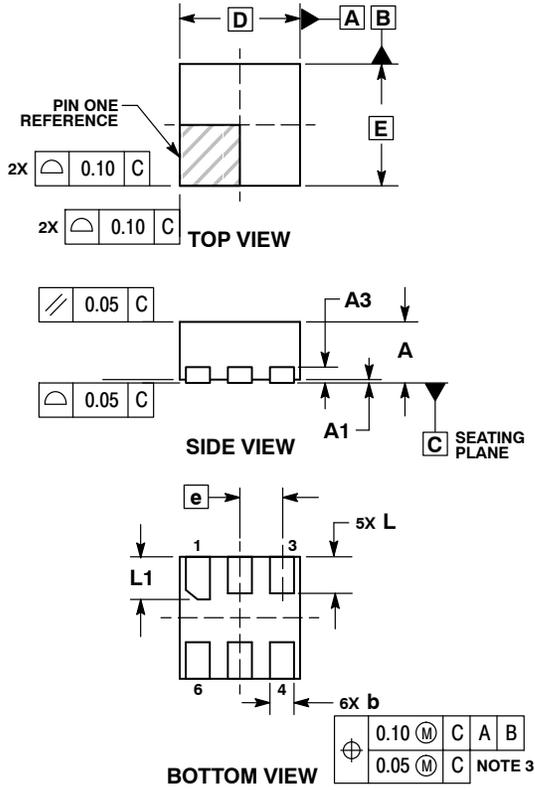
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NLU1G07

## PACKAGE DIMENSIONS

UDFN6 1.0x1.0, 0.35P  
CASE 517BX  
ISSUE O

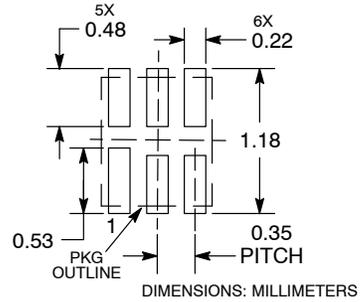


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

**RECOMMENDED SOLDERING FOOTPRINT\***



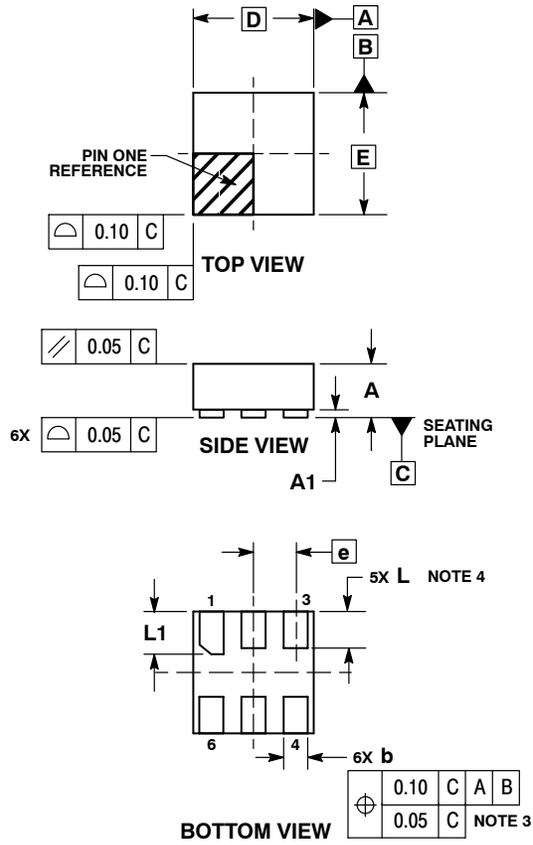
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



# NLU1G07

## PACKAGE DIMENSIONS

ULLGA6 1.0x1.0, 0.35P  
CASE 613AD  
ISSUE A

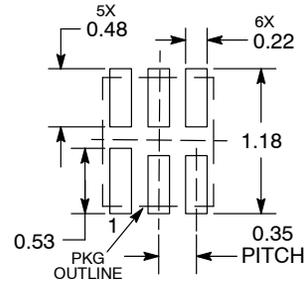


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 mm PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

### MOUNTING FOOTPRINT SOLDERMASK DEFINED\*



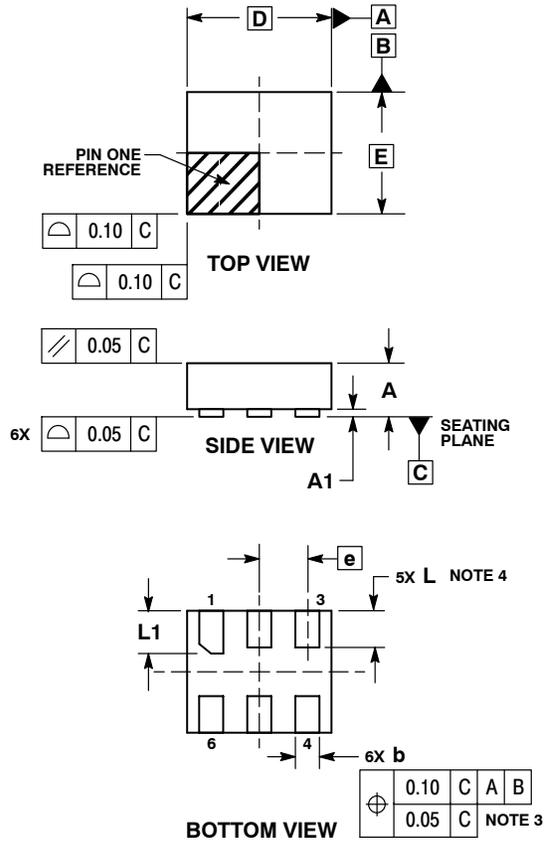
DIMENSIONS: MILLIMETERS

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## PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P  
CASE 613AE  
ISSUE A

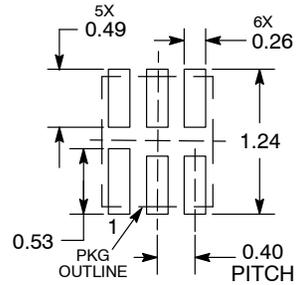


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MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

**MOUNTING FOOTPRINT  
SOLDERMASK DEFINED\***



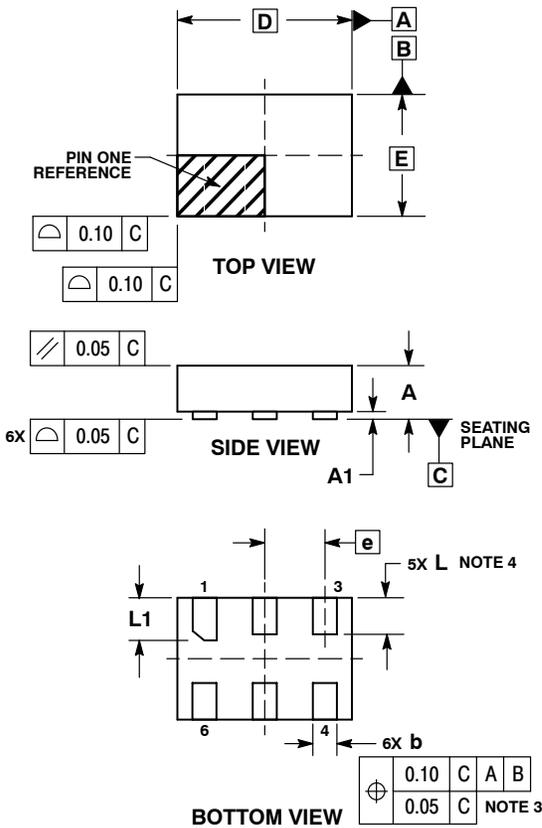
DIMENSIONS: MILLIMETERS

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## PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P  
CASE 613AF  
ISSUE A

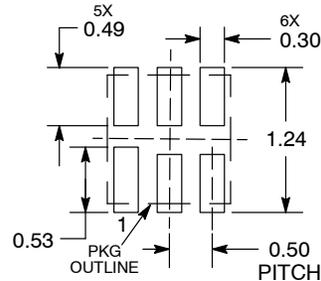


### NOTES:

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MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

### MOUNTING FOOTPRINT SOLDERMASK DEFINED\*



DIMENSIONS: MILLIMETERS

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